

## Electroplating System

### ***Specifications:***

- Pump & Filter Flo-King pump (Lab), 400 Gal/Hr maximum with 1 micron filter - cartridge 4" long, 1.5" diameter. 5 filter replacement spare parts included
- Heater -Thermostat Temperature Controller with 550 Watt heater and chemically inert capable maintaining within 1 deg C solution temperature
- Reciprocating Mechanism Regulator enables the operator to fine-tune the frequency of the FIBRoPlate™ Reciprocating Anode. The range of the frequency is 0 - 2.7 Hz
- Reciprocating Anode One reciprocating FIBRoPlate™ insoluble Pt/Ti anode selected from the range of 2" to 8" dia. with fibrous applicator to regulate transport of matter and electric field distribution
- Wafer Holder One two part assembly with circular contact for electroplating wafers of one diameter selected from the range 2" to 8"
- Exhaust attachment 2" to 6" (TBD) hood attachment extension on side of Power Section
- Hull Cell + anode QC device for control and maintenance of electroplating solution Process capabilities

### ***Substrates used:***

- Si or any other material that could be plated. At present Cu and Ag are plated on Ni deposited samples. Pulse and continuous plating is possible using digital power supply. Feature as tin as 5 um could be easily plated.
- **Substrate size:** 5 inches diameter wafer maximum
- **Substrate temperature:** 60-70C
- **Materials that can be deposited:** Ni, Cu, Ag, Au
- Materials can be deposited but targets NOT available: Ag